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ABSTRACT

NOVEL METHOD TO MINIMIZE ISO-DENSE CONTACT OR VIA GAP FILLING VARIATION OF POLYMERIC MATERIALS IN THE SPIN COAT PROCESS

A method for spin coating a polymeric material film upon a wafer rotatably mounted within a spin coater; the wafer having a surface, including the following steps. A first step of rotating the wafer on an axis perpendicular to the wafer surface while applying a predetermined amount of polymeric material while rotating the wafer at a rotational speed of from about 300 to 1200 rpm for from about 2.5 to 5 seconds to spread the polymeric material on the whole surface of the wafer. A second step of increasing the rotational speed of the wafer to about 5500 rpm for about 2.5 seconds. A third step of decreasing the rotational speed of the wafer to about 300 to 1200 rpm for about 2.5 seconds. A fourth step of increasing the rotational speed of the wafer to about 5500 rpm for about 20 seconds to form the polymeric material film having a predetermined thickness over the whole surface of the wafer.

(Fig. 5)



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